

*Amendments to the Claims*

This listing of claims will replace all prior versions, and listings of claims in the application.

1. (Currently amended) A method for the manufacture of a piezoelectric element, comprising:

a step of forming a diaphragm on a substrate;

a step of forming a bottom electrode on said diaphragm;

a step of forming a first piezoelectric layer constituting a part of a piezoelectric film on said bottom electrode;

a step of patterning said first piezoelectric layer and said bottom electrode to a prescribed shape;

a step of forming a second piezoelectric layer constituting another part of the piezoelectric film on a remaining portion of said first piezoelectric layer that was left by said patterning and said diaphragm exposed by said patterning ~~from which said first piezoelectric layer was removed~~; and

a step of forming a top electrode on said piezoelectric film.

2. (Original) The method for the manufacture of a piezoelectric element according to claim 1,

wherein the thickness of said first piezoelectric layer is less than the thickness of said second piezoelectric layer.

3. (Original) The method for the manufacture of a piezoelectric element according to claim 1, additionally comprising a step of forming a Ti layer after said step of patterning and prior to said step of forming a second piezoelectric layer, wherein said Ti layer has a thickness of no less than 1 nm and no more than 4 nm.

4-15 (Canceled).